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(12) **United States Design Patent** (10) **Patent No.:** **US D925,448 S**
Frank et al. (45) **Date of Patent:** **** Jul. 20, 2021**

(54) **POWERCORE MODULE**

(56) **References Cited**

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(**) Term: **15 Years**

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(21) Appl. No.: **29/744,499**

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Related U.S. Application Data

(62) Division of application No. 29/671,570, filed on Nov. 28, 2018, now Pat. No. Des. 906,240.

(57) **CLAIM**

The ornamental design for a powercore module, as shown and described.

Foreign Application Priority Data

Jun. 4, 2018 (DE) 40 2018 100 537.1

DESCRIPTION

(51) **LOC (13) Cl.** **13-02**

(52) **U.S. Cl.**
USPC **D13/110**

(58) **Field of Classification Search**
USPC D13/102, 110, 112, 116; D14/188, 189; D24/170, 232, 144, 138, 169; D26/44, D26/45, 46, 47, 48, 49, 50
CPC A61B 18/1206; A61B 18/1402; A61B 18/1815; H01R 13/641; G05B 15/02
See application file for complete search history.

FIG. 1 is a front, top, perspective view of a powercore module.

FIG. 2 is a top plan view thereof.

FIG. 3 is a bottom plan view thereof.

FIG. 4 is a front view thereof.

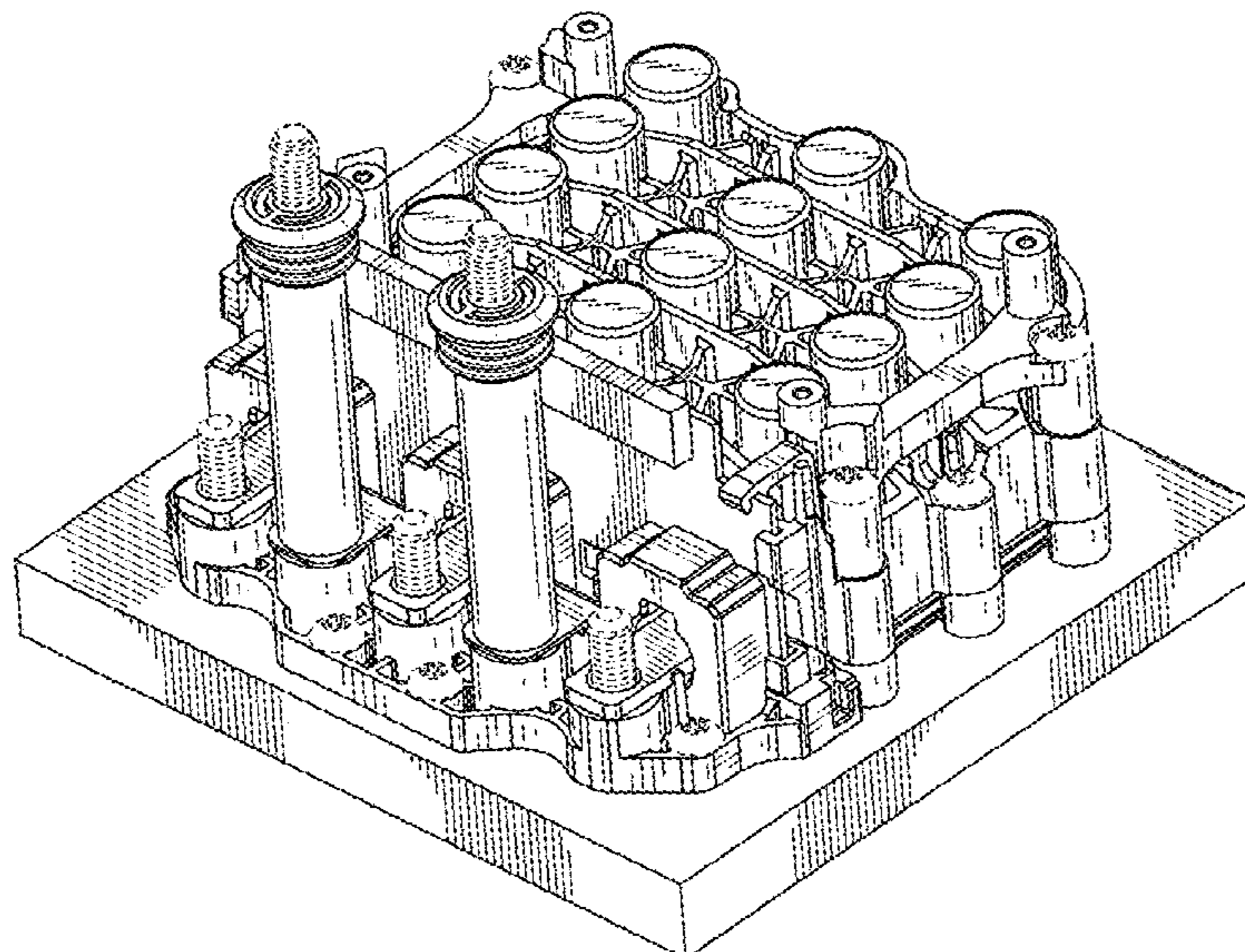
FIG. 5 is a rear view thereof.

FIG. 6 is a right side view thereof; and,

FIG. 7 is a left side view thereof.

No claim is made to portions which are not shown. The dash-dash disclaim lines indicate portions to which no claim is made. The surface is lightly lined for contour.

1 Claim, 7 Drawing Sheets



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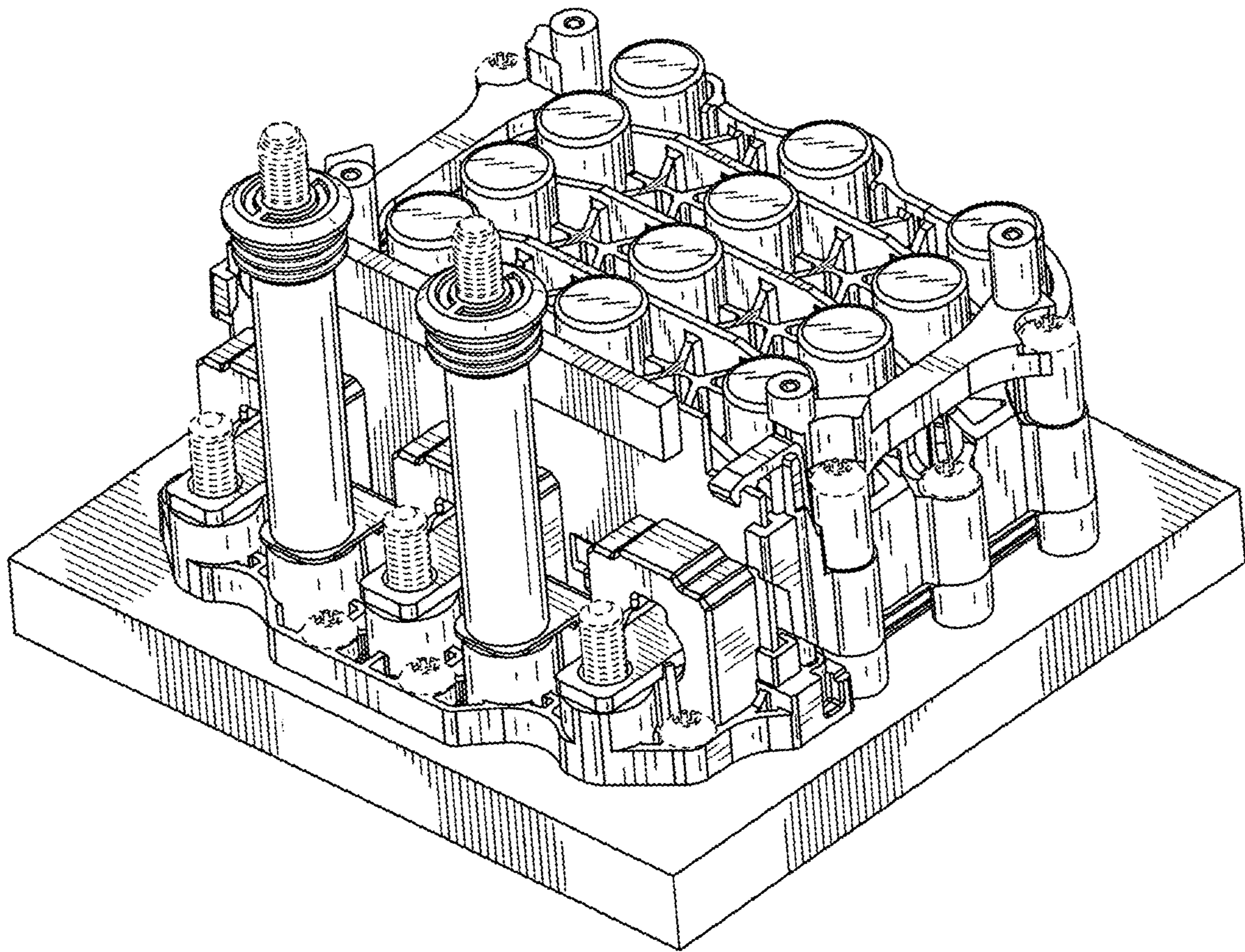


FIG. 1

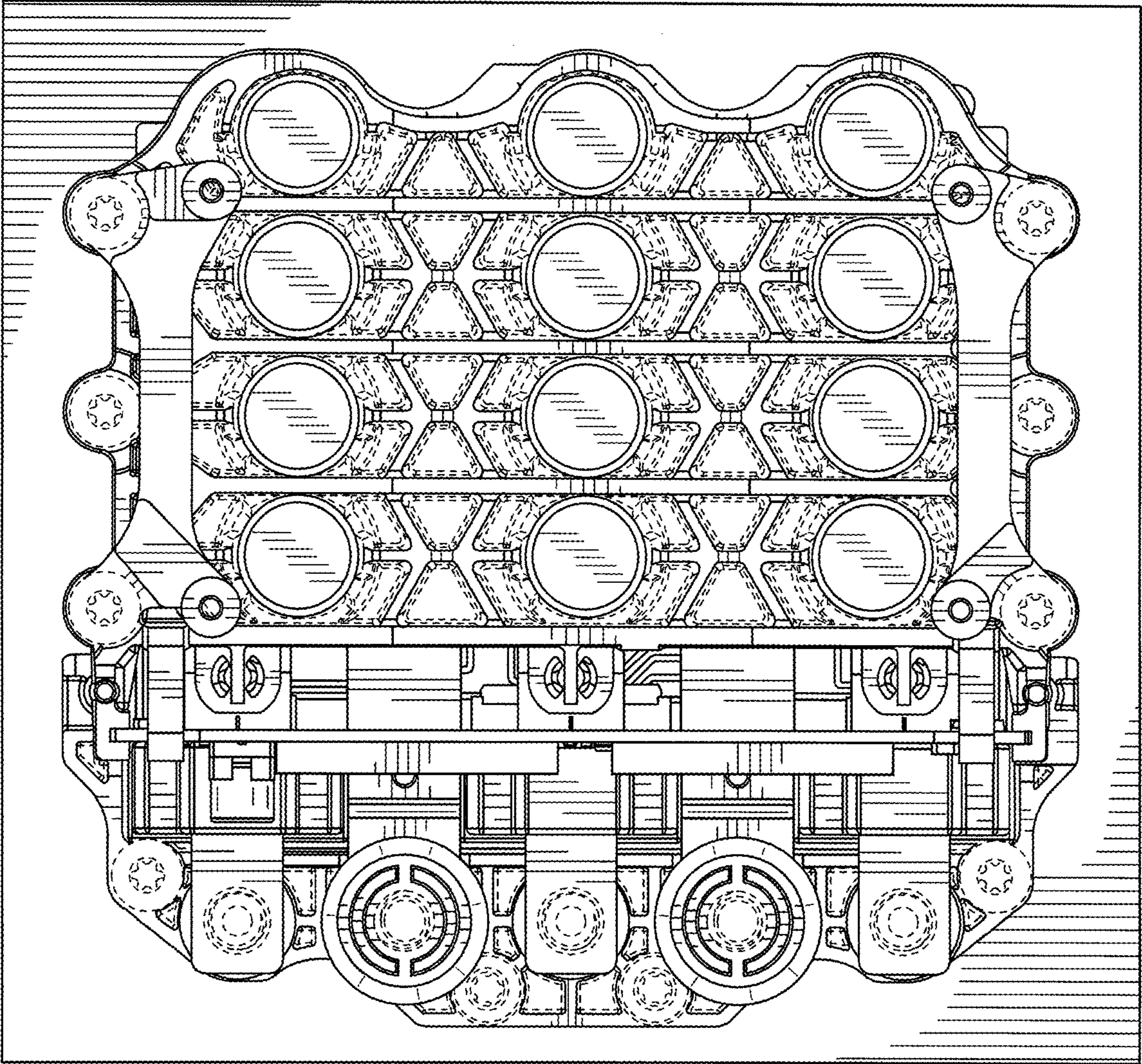


FIG. 2

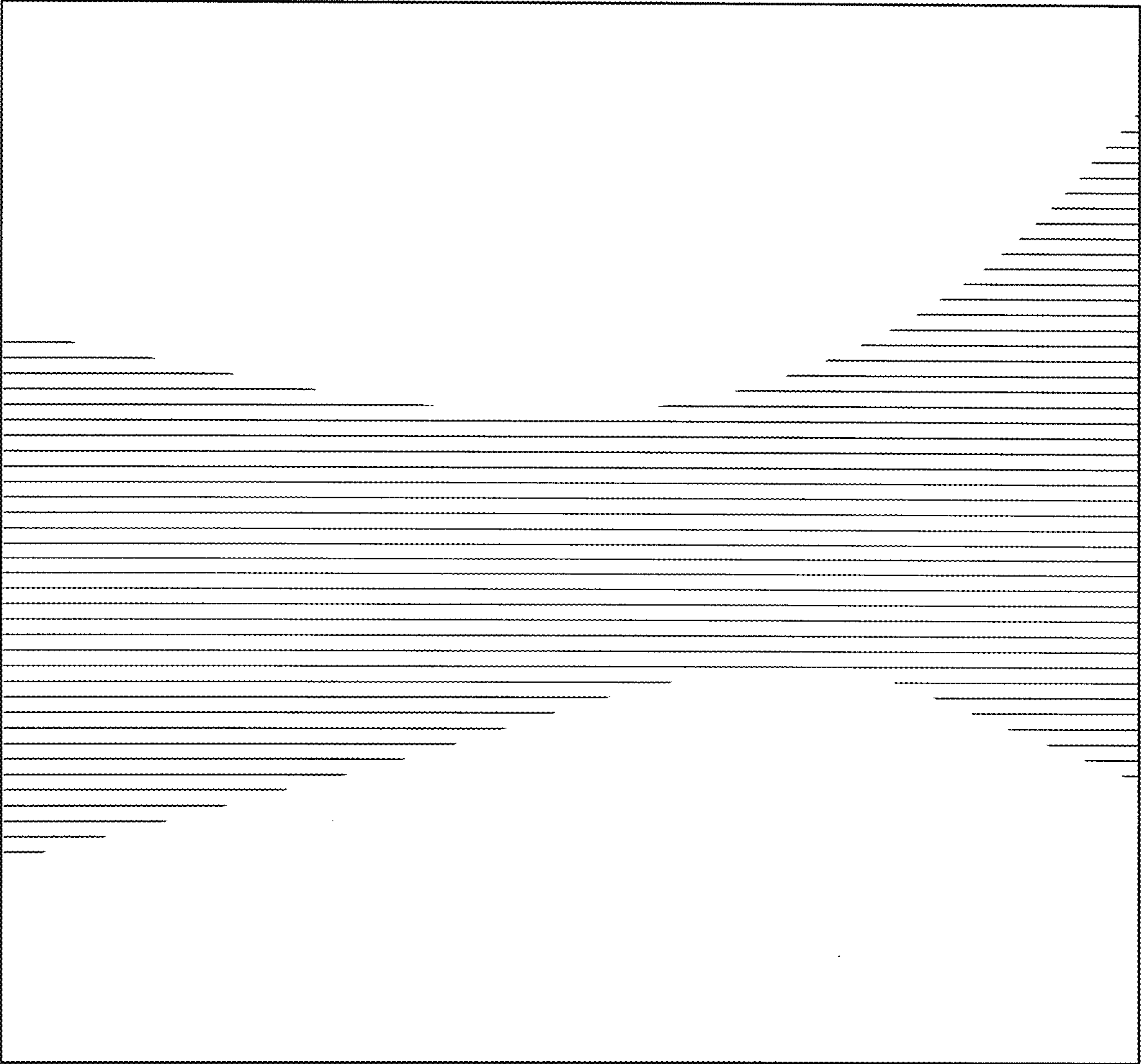


FIG. 3

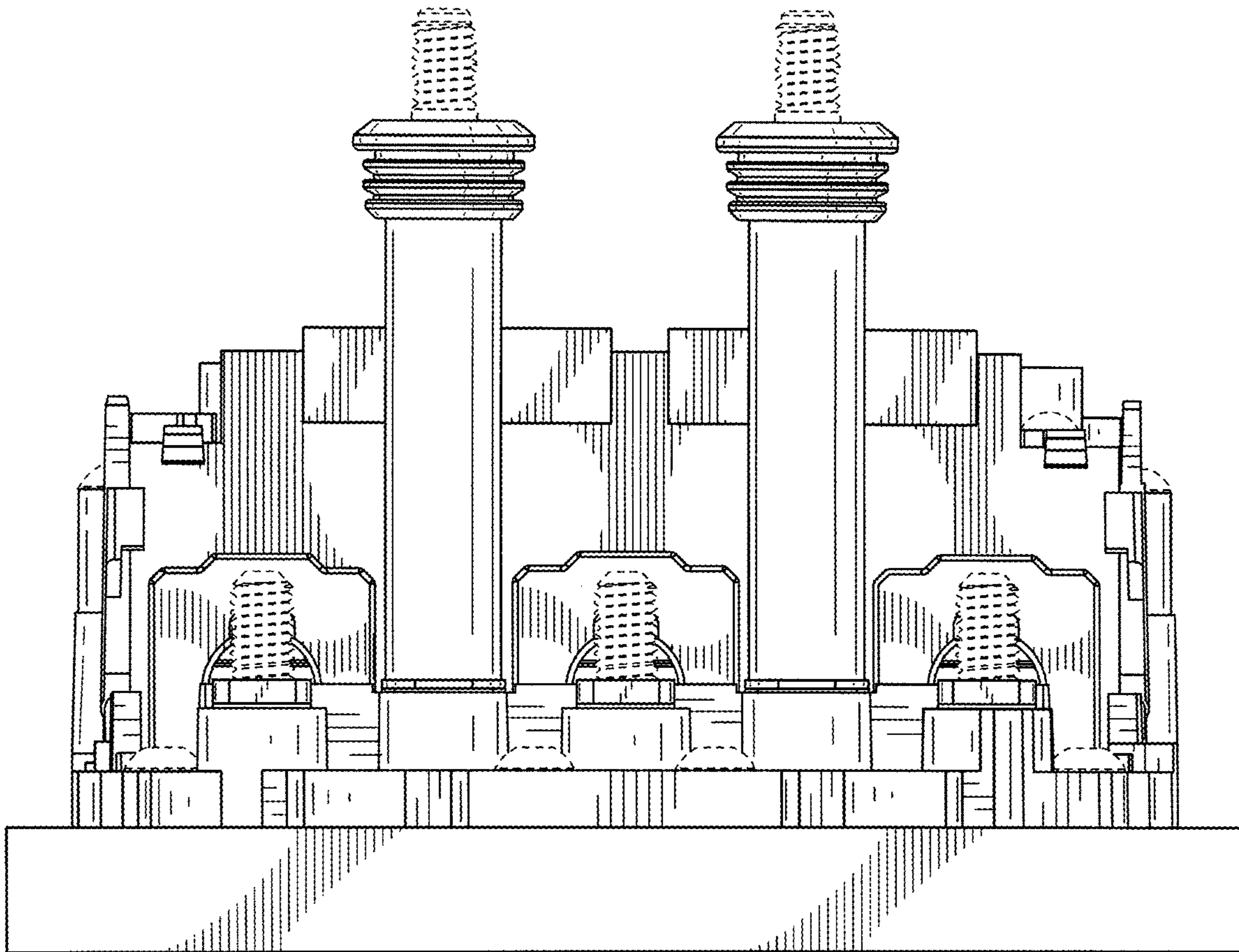


FIG. 4

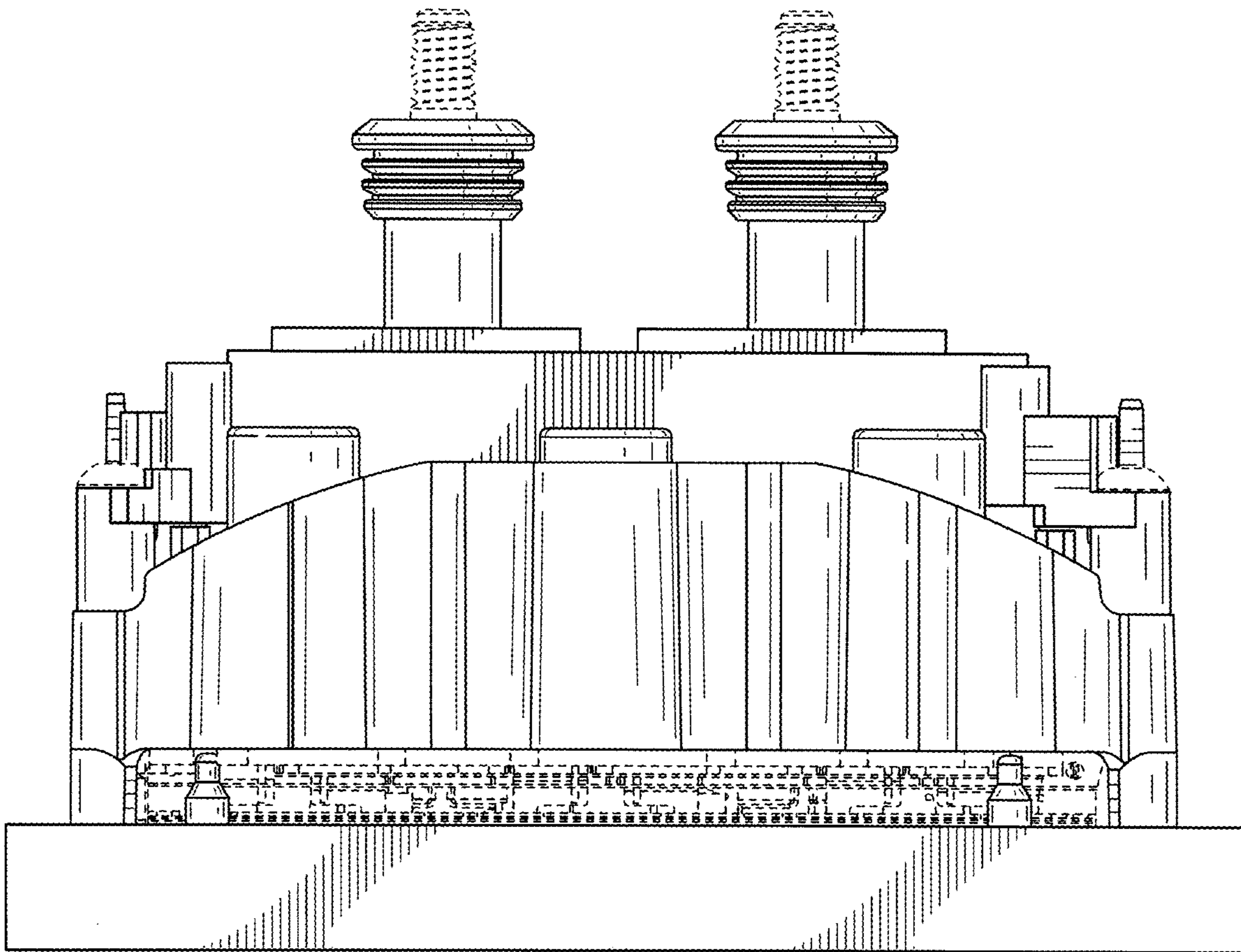


FIG. 5

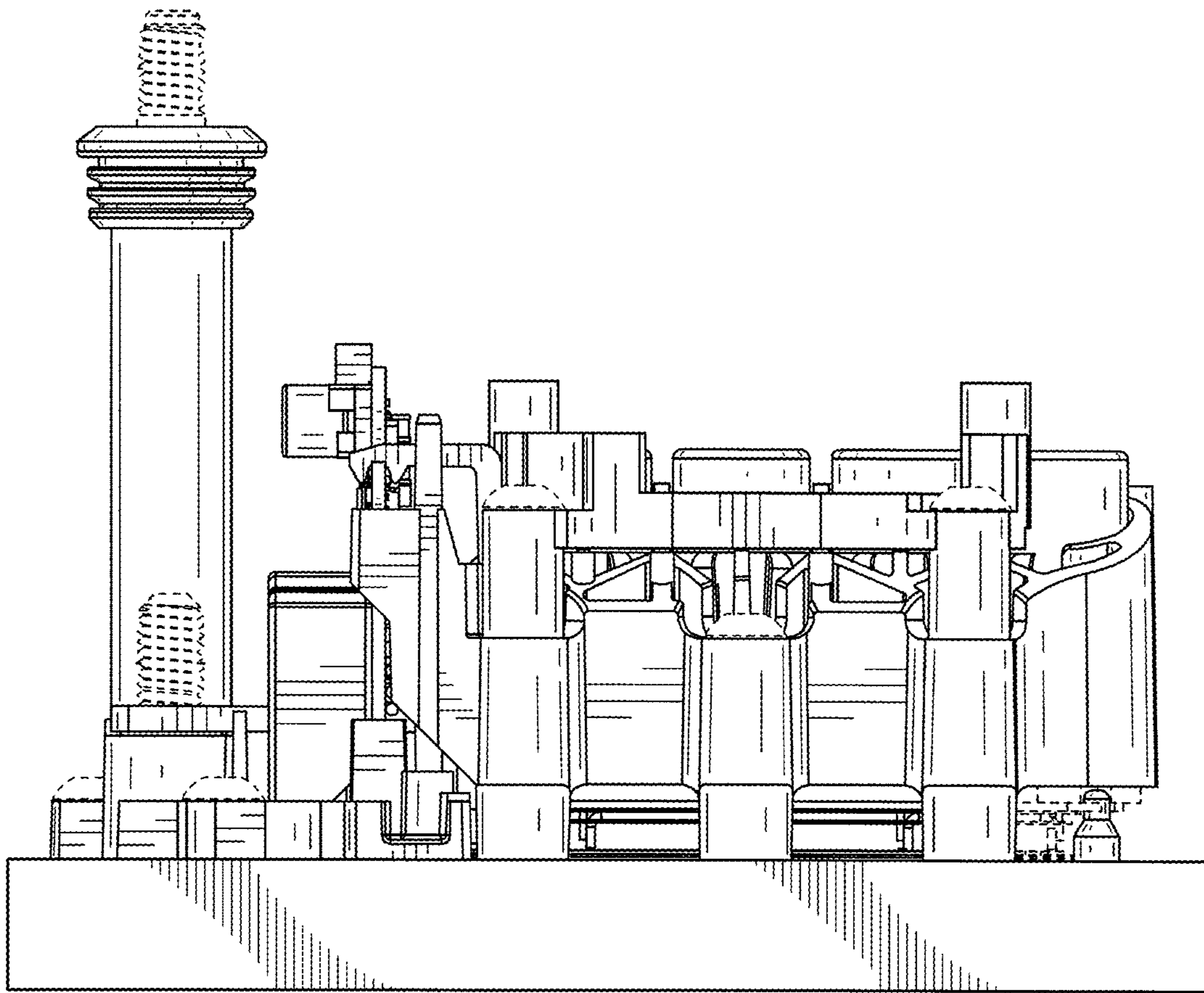


FIG. 6

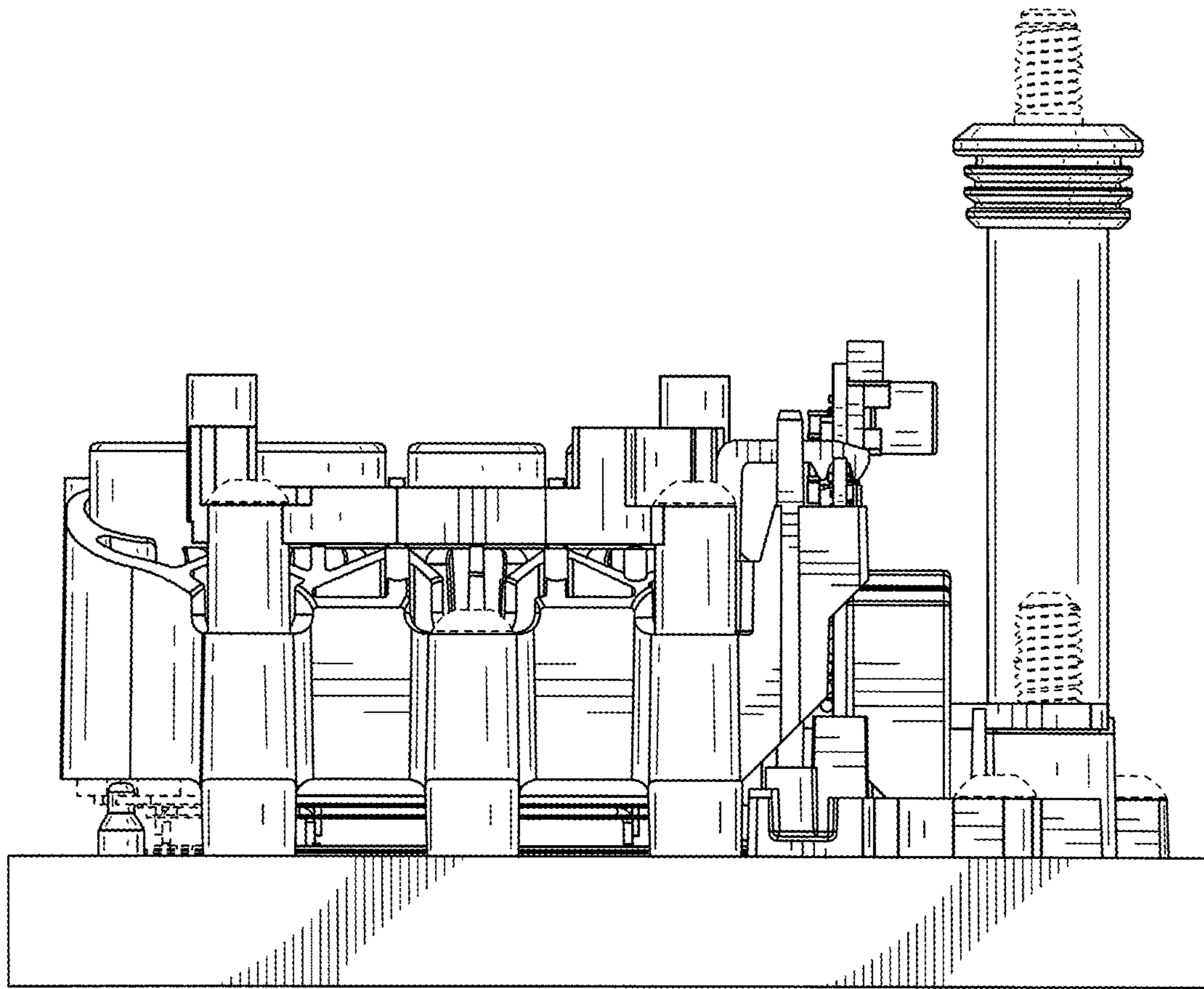


FIG. 7